Customers PCI Early Notification

Reference DMS Number: DM01249819

Purpose & Content

This Corporate Product / Process change information provides ***early notification*** *on ST Logistic adaptation following ST acquisition of NXP's MEMS sensors business*

1 Logistic adaptations

2 Appendix – detailed documentation

Logistic adaptations

As of March 30th onwards, ST will progressively implement changes to the physical specifications of **all NXP-produced goods**

🟨 = Detailed next

As-is flow

#		Supply Chain activity As-is	Requirement As-is
🟨 1a	NXP / OSAT Mfg.	**Reel label**	NXP
🟨 2a		**MBB[1] label**	NXP
🟨 3a		**Inner Box**	NXP
🟨 4a		**Inner Box label**	NXP
5a		Shipment to WH	n/a
6a	NXP WH/ DC	**Client custom label**	NXP
🟨 7a		**Outer Box**	NXP
🟨 8a		**Outer Box label**	NXP
9a		**Shipping documents[2]**	NXP
10a		Shipment to Regional DC[3]	NXP
		End customer	n/a

To-be flow[6]

#		Supply Chain activity To-be	Requirement To-be	ETA
🟨 1b	NXP / OSAT Mfg.	Change **Reel label**	NXP w/ ST header	30th Mar
🟨 2b		Change **MBB[1] label**	NXP w/ ST header	30th Mar
🟨 3b		Change **Inner Box**	ST 's artwork w/ NXP dimension	1st Jun[4]
🟨 4b		Change **Inner Box label**	NXP w/ ST header	30th Mar
5b		Shipment to WH	n/a	
🟨 6b	NXP WH	Add **ST label** (MBB[1]/inner box)	ST 's label: 1x inner box 2x MBB (as peel-off)[5]	30th Mar
7b		**Outer Box**	n/a	
8b		**Outer Box label**	n/a	
9b		**Shipping documents[2]**	n/a	
10b		Shipment to ST	n/a	
11b	ST WH / DC	Adapt **Client custom label**	ST	30th Mar
🟨 12b		Adapt **Outer Box**	ST	30th Mar
🟨 13b		Adapt **Outer Box label**	ST	30th Mar
14b		Adapt **Shipping documents[2]**	ST	30th Mar
15b		Shipment to Regional DC[3]	ST	30th Mar
		End customer	n/a	

---

1. Moisture Bag Barrier
2. Inlcuding: Invoice, Packing list and Delivery note (optional)
3. Additional packing list is produced/ replaced by DC and delivered to customer
4. Subject to possibility of repacking of existing inventory
5. One to be applied to Reel by the customer if necessary to them
6. Not including Legacy Pressure product family

Note: Presence of trademark propriety of NXP, used by STMicroeletronics under license

Specific **only to the "Legacy Pressure"[7] product family**, as of March 30th onwards, ST will progressively implement the following changes:

xx = Specific to "Legacy Pressure"[7] product family 🟨 = Detailed next

As-is flow

#		Supply Chain activity As-is	Requirement As-is
1a	OSAT Mfg.	**Reel label**	NXP
2a	OSAT Mfg.	**MBB[1] label**	NXP
3a	OSAT Mfg.	**Inner Box**	NXP
4a	OSAT Mfg.	**Inner Box label**	NXP
5a		Shipment to WH	n/a
6a	NXP WH/ DC	**Client custom label**	NXP
7a	NXP WH/ DC	**Outer Box**	NXP
8a	NXP WH/ DC	**Outer Box label**	NXP
9a	NXP WH/ DC	**Shipping documents[2]**	NXP
10a	NXP WH/ DC	Shipment to Regional DC[3]	NXP
		End customer	n/a

To-be flow[6]

#		Supply Chain activity To-be	Requirement To-be	ETA
1b*	OSAT Mfg.	Adapt **Reel label**	ST	30th Mar
2b*	OSAT Mfg.	Adapt **MBB[1] label**	ST	30th Mar
3b*	OSAT Mfg.	Adapt **Inner Box**	ST	27th Apr[4]
4b*	OSAT Mfg.	Adapt **Inner Box label**	ST	30th Mar
10b		Shipment to WH	n/a	
11b	ST WH/ DC	Adapt **Client custom label**	ST	30th Mar
12b	ST WH/ DC	Adapt **Outer Box**	ST	30th Mar
13b	ST WH/ DC	Adapt **Outer Box label**	ST	30th Mar
14b	ST WH/ DC	Adapt **Shipping documents[2]**	ST	30th Mar
15b	ST WH/ DC	Shipment to Regional DC[3]	ST	30th Mar
		End customer	n/a	

1. Moisture Bag Barrier
2. Inlcuding: Invoice, Packing list and Delivery note (optional)
3. Additional packing list is produced/ replaced by DC and delivered to customer
4. Subject to possibility of repacking of existing inventory
5. One to be applied to Reel by the customer if necessary to them
6. Not including Legacy Pressure product family
7. Including: Pressure C-UC CP, Pressure C-UC UB, Pressure IPS SM, Pressure IPS SOP LP, Pressure-IPS-SM-A, Pressure BP COMP, Pressure IPS UB, Pressure C-UC SM

Note: Presence of trademark propriety of NXP, used by STMicroeletronics under license

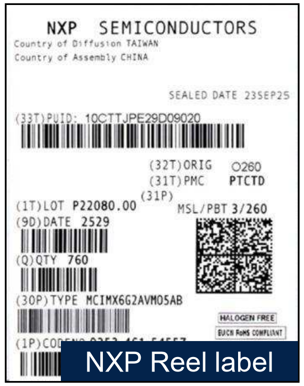
Appendix – detailed documentation

Detailed documentation: Reel label 1a vs. 1b

DUMMY EXAMPLE – USED FOR EXPLAINATORY PURPOSES

As-is flow

1a



NXP SEMICONDUCTORS
Country of Diffusion TAIWAN
Country of Assembly CHINA
SEALED DATE 23SEP25
(33T)PUID: 10CTTJPE29D09020
(32T)ORIG O260
(31T)PMC PTCTD
(31P)
(1T)LOT P22080.00
MSL/PBT 3/260
(9D)DATE 2529
(Q)QTY 760
(30P)TYPE MCIMX6G2AVM05AB
HALOGEN FREE
EU RoHS COMPLIANT
(1P)COD

NXP Reel label

To-be flow

1b

STMicroelectronics
Country of Diffusion Taiwan
Country of Assembly Malaysia
SEALED DATE 31DEC25
(33T)PUID: 01TSKLPE52BNV000
(32T)ORIG 0640
(31T)PMC PTQ-D
(30D)DATE2 2552
(31P)
MSL/PBT 3/260
(1T)LOT P24780.00
(9D)DATE 2552
(Q)QTY 500
(30P)TYPE SGMPC7384D5MVUR
(1P)CODE

NXP Reel label

\+

6b

ST Reel label (on MBB)

STMicroelectronics
Manufactured under Patents or Patents Pending
Country of Diffusion:SINGAPORE
Country of Assembly: THAILAND
PBFREE
MSL: 1
PBT: 260
TYPE: FXLS8964AFR3
Total Qty: [illegible]
Trace Codes 2534
2535
BULK ID: 0TXTH0949545
Please Provide the bulk ID for any inquiries

Note: This label will be pasted on **MBB[1] as peel-off**

Main changes for customer:

- The existing **NXP Inner Box label** header will be rebranded from "NXP SEMICONDUCTORS" to "STMicroeletronics“.
- **ST Reel label** will be pasted on the MBB[1], aligned with ST standards, with only minor formatting / content differences.
- Customers are **requested to use only the ST inner box label**. The rebranded NXP label should be used for reference purposes only.
- ST Reel label pasted on the MBB[1] is a **peel-off label**. If required, **customers should manually transfer the label from the MBB[1] to the reel**

---

1. Moisture Bag Barrier

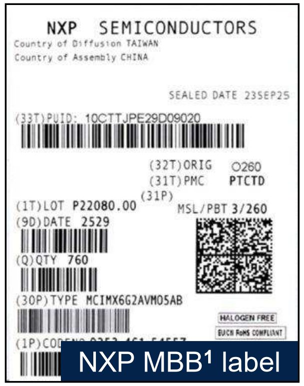
Note: Presence of trademark propriety of NXP, used by STMicroeletronics under license

Detailed documentation: MBB label 2a vs. 2b

DUMMY EXAMPLE – USED FOR EXPLAINATORY PURPOSES

As-is flow

2a



NXP SEMICONDUCTORS
Country of Diffusion TAIWAN
Country of Assembly CHINA
SEALED DATE 23SEP25
(33T)PUID: 10CTTJPE29D09020
(32T)ORIG O260
(31T)PMC PTCTD
(31P)
(1T)LOT P22080.00
MSL/PBT 3/260
(9D)DATE 2529
(Q)QTY 760
(30P)TYPE MCIMX6G2AVM05AB
HALOGEN FREE
EU RoHS COMPLIANT
(1P)COD

NXP MBB[1] label

To-be flow

2b

STMicroelectronics
Country of Diffusion Taiwan
Country of Assembly Malaysia
SEALED DATE 31DEC25
(33T)PUID: 01TSKLPE52BNV000
(32T)ORIG 0640
(31T)PMC PTQ-D
(30D)DATE2 2552
(31P)
(1T)LOT P24780.00
MSL/PBT 3/260
(9D)DATE 2552
(Q)QTY 500
(30P)TYPE SGMPC7384D5MVUR
(1P)COD

NXP MBB[1] label

\+

6b

2 x ST MBB[1]/ Reel label (on MBB)

STMicroelectronics
Manufactured under Patents or Patents Pending
Country of Diffusion:SINGAPORE
Country of Assembly: THAILAND
PBFREE
MSL: 1
PBT: 260
TYPE: FXLS8964AFR3
FXLS8964AF
Total Qty: 6000
Trace Codes 2534
2535
BULK ID: 0TXTH0949545
Please Provide the bulk ID for any inquiries

Note: Two additional labels will be pasted on **MBB[1] as peel-off for Reel label and MBB[1] label**

Main changes for customer:

- The existing **NXP Inner Box label** header will be rebranded from "NXP SEMICONDUCTORS" to "STMicroeletronics“.
- Two additional **ST MBB/ Reel label** will be pasted, aligned with ST standards, with only minor formatting / content differences.
- Customers are **requested to use only the ST inner box label**. The rebranded NXP label should be used for reference purposes only.
- Both additional ST MBB/ Reel label are **peel-off labels**. If required, **customers should manually transfer one label from the MBB[1] to the reel**

---

1. Moisture Bag Barrier

Note: Presence of trademark propriety of NXP, used by STMicroeletronics under license

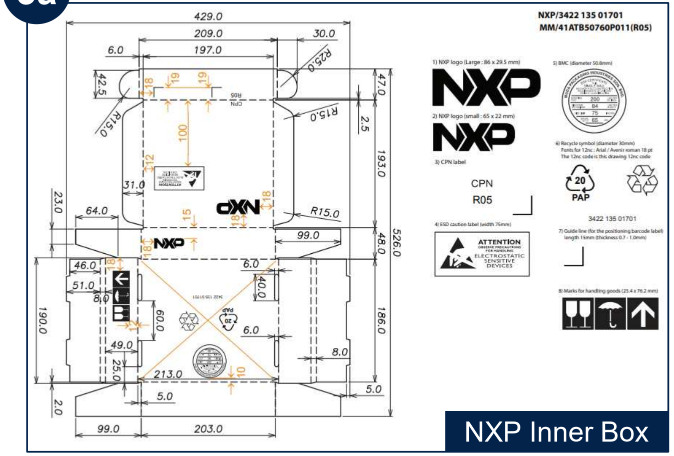
Detailed documentation: Inner Box 3a vs. 3b

DUMMY EXAMPLE – USED FOR EXPLAINATORY PURPOSES

As-is flow

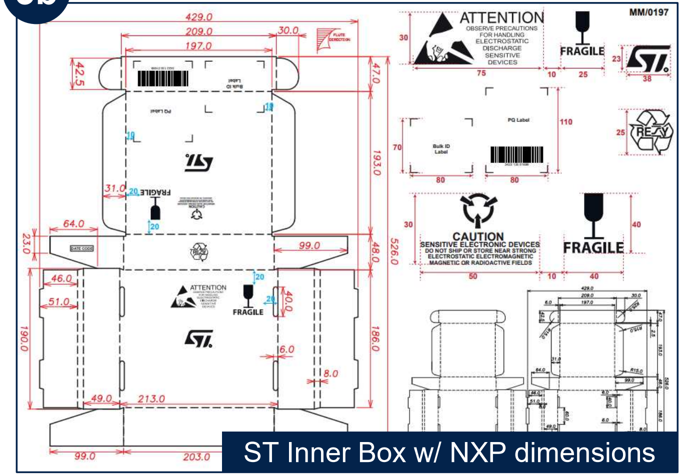
To-be flow

3a



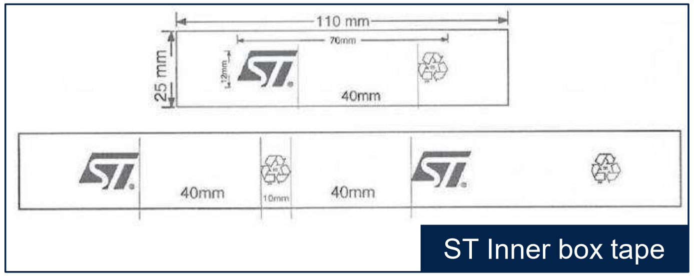
NXP Inner Box

3b



ST Inner Box w/ NXP dimensions

NXP Inner box tape



ST Inner box tape

Main changes for customer:

- The existing NXP **Inner Box artwork** will be rebranded from NXP to ST standards. Box **dimensions** will remain in line with NXP specifications. Box **material** will be updated to meet ST standards, with no impact on functionality.
- The existing NXP **Inner Box tape**, currently unbranded, will be updated to comply with ST branding standards.

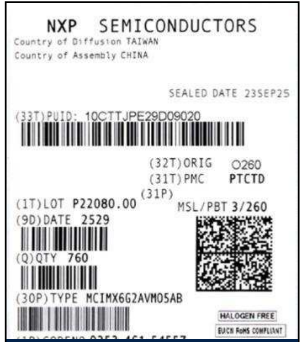
Note: Presence of trademark propriety of NXP, used by STMicroeletronics under license

Detailed documentation: Inner Box label 4a vs. 4b

DUMMY EXAMPLE – USED FOR EXPLAINATORY PURPOSES

As-is flow

4a



NXP SEMICONDUCTORS
Country of Diffusion TAIWAN
Country of Assembly CHINA

SEALED DATE 23SEP25
(33T)PUID: 10CTTJPE29D09020
(32T)ORIG O260
(31T)PMC PTCTD
(31P)
(1T)LOT P22080.00
MSL/PBT 3/260
(9D)DATE 2529
(Q)QTY 760
(30P)TYPE MCIMX6G2AVM05AB
HALOGEN FREE
EU(CN) RoHS COMPLIANT

NXP Inner Box label

To-be flow

4b

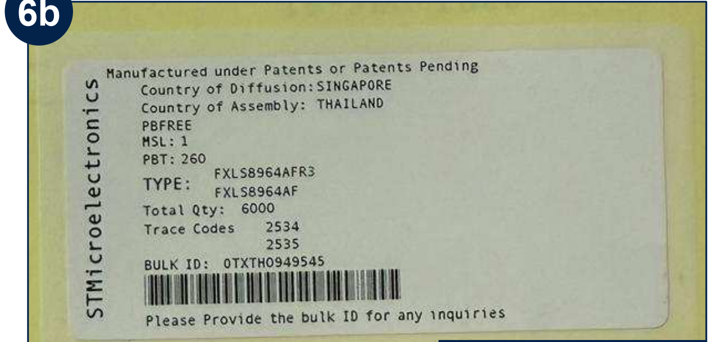
STMicroelectronics
Country of Diffusion Taiwan
Country of Assembly Malaysia

SEALED DATE 31DEC25
(33T)PUID: 01TSKLPE52BNV000
(32T)ORIG 0640
(31T)PMC PTQ-D
(30D)DATE2 2552
(31P)
MSL/PBT 3/260
(1T)LOT P24780.00
(9D)DATE 2552
(Q)QTY 500
(30P)TYPE SGMPC7384D5MVUR

NXP Inner Box label

+

6b



STMicroelectronics
Manufactured under Patents or Patents Pending
Country of Diffusion: SINGAPORE
Country of Assembly: THAILAND
PBFREE
MSL: 1
PBT: 260
TYPE: FXLS8964AFR3
FXLS8964AF
Total Qty: 6000
Trace Codes 2534
2535
BULK ID: 0TXTH0949545
Please Provide the bulk ID for any inquiries

ST Inner Box label

Main changes for customer:

- The existing **NXP Inner Box label** header will be rebranded from "NXP SEMICONDUCTORS" to "STMicroeletronics“.
- An additional **ST Inner Box label** will be pasted, aligned with ST standards, with only minor formatting/ content differences.
- Customers are **requested to use only the ST inner box label**. The rebranded NXP label should be used for reference purposes only.

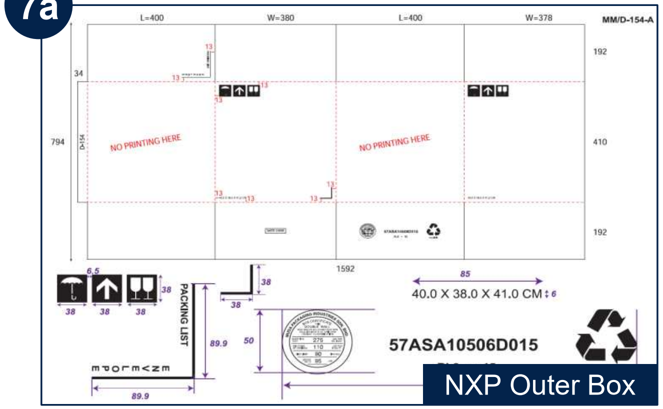
Note: Presence of trademark propriety of NXP, used by STMicroeletronics under license

Detailed documentation: Outer Box 7a vs. 12b

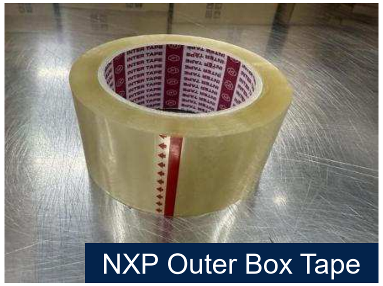
DUMMY EXAMPLE – USED FOR EXPLAINATORY PURPOSES

As-is flow

7a



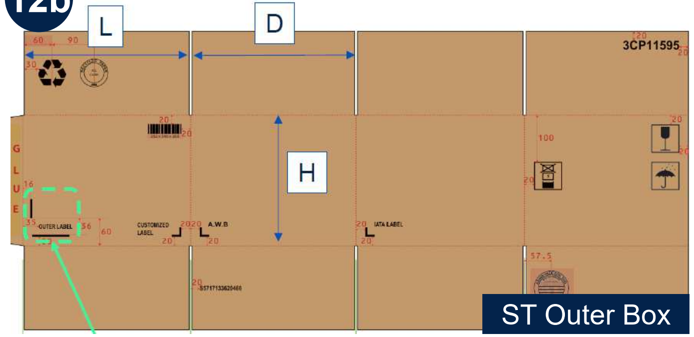
NXP Outer Box



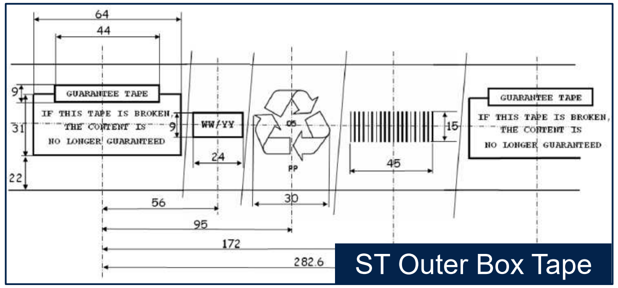
NXP Outer Box Tape

To-be flow

12b



ST Outer Box



ST Outer Box Tape

Main changes for customer:

- The existing **NXP Outer Box/ Tape** will be replaced with ST standard Outer Box/ Tape (incl. possible change in dimensions)

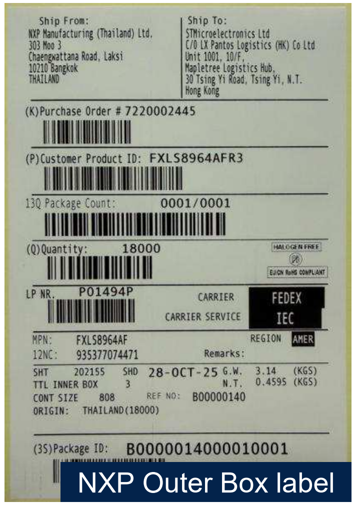
Note: Presence of trademark propriety of NXP, used by STMicroeletronics under license

Detailed documentation: Outer Box label 8a vs. 13b

DUMMY EXAMPLE – USED FOR EXPLAINATORY PURPOSES

As-is flow

8a



Ship From:
NXP Manufacturing (Thailand) Ltd.
303 Moo 3
Chaengwattana Road, Laksi
10210 Bangkok
THAILAND

Ship To:
STMicroelectronics Ltd
C/O LX Pantos Logistics (HK) Co Ltd
Unit 1001, 10/F,
Mapletree Logistics Hub,
30 Tsing Yi Road, Tsing Yi, N.T.
Hong Kong

(K)Purchase Order # 7220002445

(P)Customer Product ID: FXLS8964AFR3

13Q Package Count: 0001/0001

(Q)Quantity: 18000

HALOGEN FREE
EU/CN RoHS COMPLIANT

LP NR. P01494P

CARRIER FEDEX
CARRIER SERVICE IEC

MPN: FXLS8964AF
12NC: 935377074471
REGION AMER
Remarks:

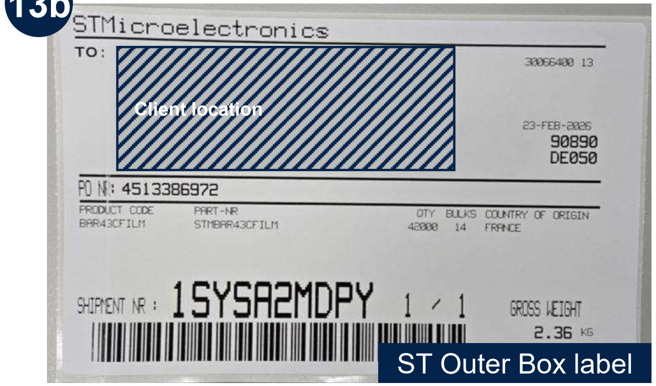
SHT 202155 SHD 28-OCT-25 G.W. 3.14 (KGS)
TTL INNER BOX 3 N.T. 0.4595 (KGS)
CONT SIZE 808 REF NO: B00000140
ORIGIN: THAILAND(18000)

(3S)Package ID: B0000014000010001

NXP Outer Box label

To-be flow

13b



STMicroelectronics

TO: Client location

30066400 13

23-FEB-2026
90890
DE050

PO NR: 4513386972

PRODUCT CODE	PART-NR	QTY	BULKS	COUNTRY OF ORIGIN
BAR43CFILM	STMBAR43CFILM	42000	14	FRANCE

SHIPMENT NR : 1SYSA2MDPY 1 / 1

GROSS WEIGHT
2.36 KG

ST Outer Box label

Main changes for customer:

- The existing **NXP Outer Box label** will be replaced with ST standard Outer label

Note: Presence of trademark propriety of NXP, used by STMicroeletronics under license

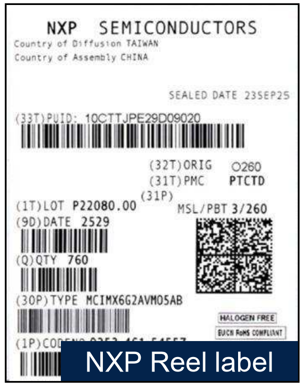
ST Restricted

Detailed documentation: Reel label 1a vs. 1b*

DUMMY EXAMPLE – USED FOR EXPLAINATORY PURPOSES

As-is flow

1a



NXP SEMICONDUCTORS
Country of Diffusion TAIWAN
Country of Assembly CHINA

SEALED DATE 23SEP25
(33T)PUID: 10CTTJPE29D09020
(32T)ORIG O260
(31T)PMC PTCTD
(31P)
(1T)LOT P22080.00
MSL/PBT 3/260
(9D)DATE 2529
(Q)QTY 760
(30P)TYPE MCIMX6G2AVM05AB
HALOGEN FREE
EU RoHS COMPLIANT
(1P)COD

NXP Reel label

To-be flow (only for Legacy Pressure)

1b*

Manufactured under patents or patents pending
STMicroelectronics
Country of Origin: MALAYSIA
Pb-free 2nd Level Interconnect
MSL: 3 Bag seal date: 14 NOV 2012
PBT: 245 C Category: e3 ECOPACK2/RoHS

TYPE: L9403
L9403-B3/
Total Qty: 200
Trace Codes 992290PE V1 99
992290PA V1 99

Marking UT43
BULK ID T2946J0D0002
Please provide the bu

ST Reel label

Main changes for customer:

- The existing **NXP Reel label** will be replaced with ST standard Reel label

---

1. Moisture Bag Barrier

Note: Presence of trademark propriety of NXP, used by STMicroeletronics under license

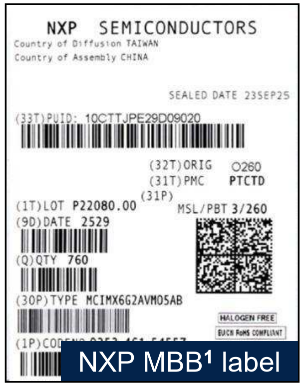
Detailed documentation: MBB label 2a vs. 2b*

DUMMY EXAMPLE – USED FOR EXPLAINATORY PURPOSES

As-is flow

To-be flow (only for Legacy Pressure)

2a



NXP SEMICONDUCTORS
Country of Diffusion TAIWAN
Country of Assembly CHINA

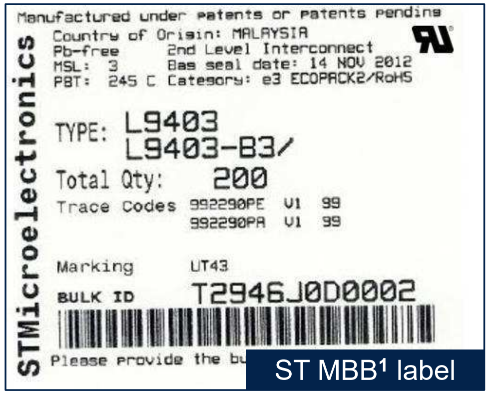
SEALED DATE 23SEP25

(33T)PUID: 10CTTJPE29D09020

(32T)ORIG O260
(31T)PMC PTCTD
(31P)
(1T)LOT P22080.00
MSL/PBT 3/260
(9D)DATE 2529
(Q)QTY 760
(30P)TYPE MCIMX6G2AVM05AB
HALOGEN FREE
EU(CN RoHS COMPLIANT
(1P)COD

NXP MBB¹ label

2b*



Manufactured under patents or patents pending
Country of Origin: MALAYSIA
Pb-free 2nd Level Interconnect
MSL: 3 Bag seal date: 14 NOV 2012
PBT: 245 C Category: e3 ECOPACK2/RoHS

STMicroelectronics

TYPE: L9403
L9403-B3/
Total Qty: 200
Trace Codes 992290PE V1 99
992290PA V1 99

Marking UT43
BULK ID T2946J0D0002

Please provide the bu

ST MBB¹ label

Main changes for customer:

- The existing **NXP MBB¹ label** will be replaced with ST standard MBB¹ label

1. Moisture Bag Barrier

Note: Presence of trademark propriety of NXP, used by STMicroeletronics under license

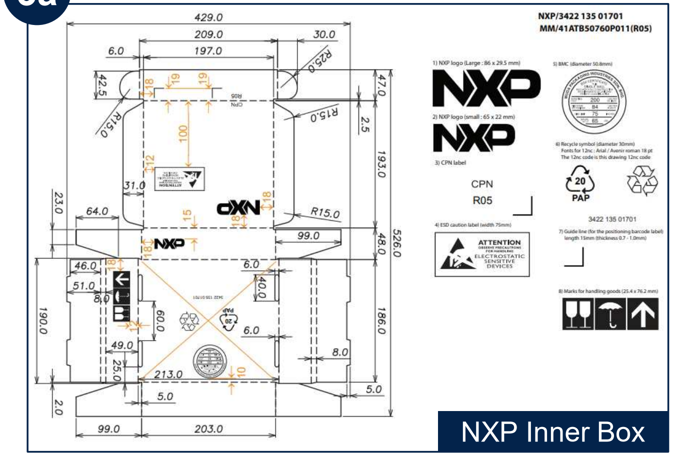
Detailed documentation: Inner Box 3a vs. 3b*

DUMMY EXAMPLE – USED FOR EXPLAINATORY PURPOSES

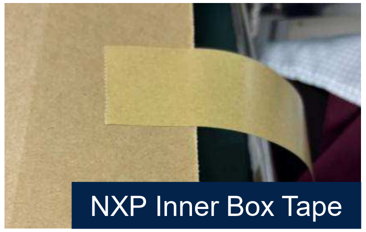
As-is flow

To-be flow (only for Legacy Pressure)

3a

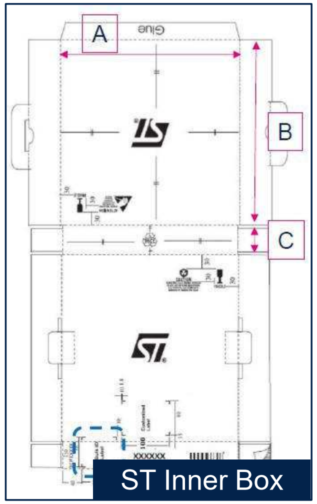


NXP Inner Box

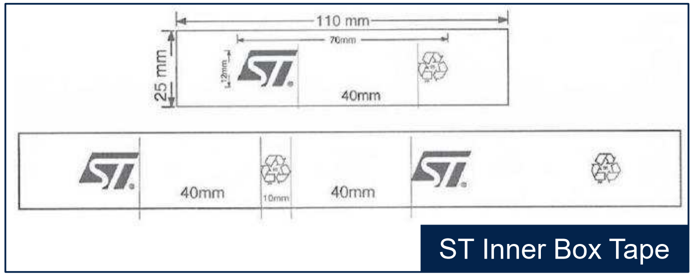


NXP Inner Box Tape

3b*



ST Inner Box



ST Inner Box Tape

Main changes for customer:

- The existing **NXP Inner Box/ Tape** will be replaced with ST standard Inner Box/ Tape (incl. possible change in dimensions)

Note: Presence of trademark propriety of NXP, used by STMicroeletronics under license

ST Restricted

Detailed documentation: Inner Box label 4a vs. 4b*

DUMMY EXAMPLE – USED FOR EXPLAINATORY PURPOSES

As-is flow

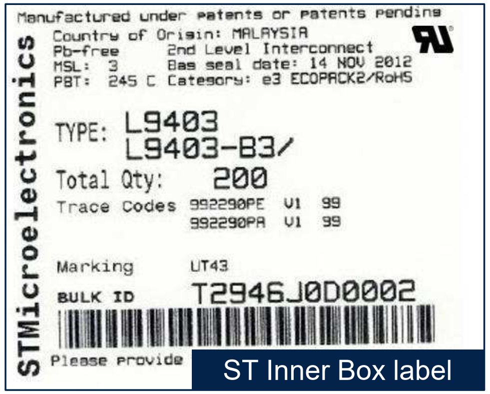
4a

NXP SEMICONDUCTORS
Country of Diffusion TAIWAN
Country of Assembly CHINA
SEALED DATE 23SEP25
(33T)PUID: 10CTTJPE29D09020
(32T)ORIG O260
(31T)PMC PTCTD
(31P)
(1T)LOT P22080.00
MSL/PBT 3/260
(9D)DATE 2529
(Q)QTY 760
(30P)TYPE MCIMX6G2AVM05AB
HALOGEN FREE
EUCN RoHS COMPLIANT

NXP Inner Box label

To-be flow (only for Legacy Pressure)

4b*



Manufactured under patents or patents pending
Country of Origin: MALAYSIA
Pb-free 2nd Level Interconnect
MSL: 3 Bag seal date: 14 NOV 2012
PBT: 245 C Category: e3 ECOPACK2/RoHS
TYPE: L9403
L9403-B3/
Total Qty: 200
Trace Codes 992290PE V1 99
992290PA V1 99
Marking UT43
BULK ID T2946J0D0002
Please provide
STMicroelectronics

ST Inner Box label

Main changes for customer:

- The existing **NXP Inner Box label** will be replaced with ST standard Inner Box label

Note: Presence of trademark propriety of NXP, used by STMicroeletronics under license

Our technology starts with You

Find out more at www.st.com

STRIVE
FOR EXCELLENCE

Product/process change notification: Logistic adaptation following ST acquisition of NXP’s MEMS sensors business

ANALOG MEMS SENSORS SUBGROUP/ APPLICATION SPECIFIC DIVISION

Description of the change

Following STMicroelectronics’ acquisition of NXP’s MEMS sensors business, **the labeling, packaging, and shipment elements** of the formerly NXP-managed products (i.e., Application Specific Division) will be transitioned to STMicroelectronics (hereinafter also referred to as “ST”) standards.

As of March 30, 2026 onwards, the following changes will be progressively implemented:

- **Reel label**: Header rebranded from "NXP SEMICONDUCTORS" to "STMicroelectronics"
- **Moisture Bag Barrier label**: Header rebranded from "NXP SEMICONDUCTORS" to "STMicroelectronics"; two additional peel-off label compliant with ST standards will be added (one copy intended for customer manual transfer to the reel, if required)
- **Inner box and tape**: Artwork/ Material updated to ST standards; dimensions remain unchanged
- **Inner box label**: Header rebranded from "NXP SEMICONDUCTORS" to "STMicroelectronics"; an additional label compliant with ST standards will be added
- **Outer box and tape**: Updated to ST standards
- **Outer box label**: Updated to ST standards
- **Packing List**: Updated to ST standards
- **Invoice**: Updated to ST standards
- **Customized label**: If needed, updated to ST standards
- **Shipping location**: ST distribution center
- **Shipping supplier**: Updated to ST standards
- **4th level packaging**: Updated to ST standards

Specific only to the "Industrial Pressure" product family, the following changes will be progressively implemented as of March 30, 2026 onwards:

- **Reel label**: Updated to ST standards
- **Moisture Bag Barrier label**: Updated to ST standards
- **Inner box and tape**: Updated to ST standards
- **Inner box label**: Updated to ST standards

Reason

Adaptation following ST acquisition of NXP’s MEMS sensors business

Date of implementation

March 30, 2026, with progressive implementation thereafter

Impact of the change

Form	Please refer to the attached presentation
Fit	n.a.
Function	n.a.
Reliability	n.a.
Processibility	n.a.

IMPORTANT NOTICE–PLEASE READ CAREFULLY

This document and all information contained herein is the property of STMicroelectronics (“ST”).

ST reserves the right to make changes, corrections, enhancements, modifications, and improvements to ST products and/or to this document at any time without notice.

This document and all information contained herein must be treated as strictly confidential and cannot be disclosed to any third party without prior written authorization from ST.

At all times you will comply with the following confidentiality rules:

- Do not copy or reproduce all or part of this document
- Keep this document locked away
- Use this document only for the purpose of your relationship with ST.

In the event of any conflict between the provisions of this document and the provisions of any contractual arrangement in force between you and ST, the provisions of such contractual arrangement shall prevail.

You should obtain the latest relevant information on ST products before placing orders. ST products are sold pursuant to ST’s terms and conditions of sale in place at the time of order acknowledgment.

You are solely responsible for the choice, selection, and use of ST products and ST assumes no liability for application assistance or the design of your products.

No license, express or implied, to any intellectual property right is granted by ST herein.

Resale of ST products with provisions different from the information set forth herein shall void any warranty granted by ST for such product.

If you identify an ST product that meets their functional and performance requirements, but that is not designated for your market segment, you shall contact ST for more information.

ST and the ST logo are trademarks of ST. For additional information about ST trademarks, you shall refer to www.st.com/trademarks. All other product or service names are the property of their respective owners.

Information in this document supersedes and replaces information previously supplied in any prior versions of this document.